KLA-Tencor Corp. Surfscan SP2

STANDARD SPECIFICATIONS

Windows System Windows XP SP3

Main S/W NGS 5.4 SR3 HF3

Wafer Size 300mm SEMI Notch

Carrier

3 AdvanTag SW CID, Phx, Shinko (load port)

8 user-conigurable LEDs to display the loadport status

Load/unload button for manual delivery hand-of

Cassette / wafer mapping which allows the tool to generate a wafer map of the 300mm FOUP and detect wafer presence, empty slots and cross-slotted wafer.

The wafer map can be displayed on the user screen and sent to a SECS host.

Facilities

Power: 208 VAC, 3W-N

CDA: > 28.3 Nl/min, > 6.6791 kg/cm2

Vac: > 28.317 l/min, > -700 mm Hg

Chamber

Powder Coat Panels Kit 200/300mm

Vacuum option Optical Filter

Load port Vacuum 300mm Tripple

FIMS Application

2mm Edge Exclusion

Oblique Incidence Illumination (High / Standard / Low)
Normal Incidence Illumination (High / Standard / Low)
Enhanced XY Coordinates
IDM SP2
Standard Classiication package

LPD-N Classiication LPD-ES
classiication Gradingand
Sorting
SpatialFilter(20degree) Spatial

Filter(40degree) Spatial ilter
(rough ilms) Spatial ilter (Back)
High Sensitivity Inspect Mode High
Throughput Inspect Mode

Options Haze
Haze Normalization Haze
Analysis
IC/OEM Mfg Surf Quality Recipe

Wafer size. 300mm XY Calibration Wafer with irst Article

HARDWARE CONFIGURATION
Others 5 Color Light Tower (RBYGW)

Ethernet NFS Client
E84 enabled for OHT & AGV/RGV E87
(Based on E39)
GEM/SECS and HSMS E40/
E94/ E90 / E116

Handler Secondary UI, Phoenix, SP2 Main

Computer
Intel®Xeon™ CPU 3.20GHz
3.5 GB RAM Memory DVD-

ROM

Mouse Keyboard

3.5" Floppy

NGS application software

FEC computer Intel®Pentium®4

CPU 512 MB RAM Memory